

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:  
a semiconductor chip diced from a semiconductor substrate with a prescribed element and an electrode portion formed on its main face and without removing a conductive film from a dicing line region;  
5 a conductive wire connected to said electrode portion; and  
an insulating sheet member for covering part of said conductive film along periphery of said semiconductor chip.
2. The semiconductor device according to claim 1, wherein  
said insulating sheet member is provided for covering a back face of  
said semiconductor chip, a side face of said semiconductor chip, and part of  
the front face along periphery of said semiconductor chip.
3. The semiconductor device according to claim 2 comprising  
a plurality of said semiconductor chips covered by said insulating  
sheet member, wherein said plurality of semiconductor chips are layered.
4. The semiconductor device according to claim 1, wherein  
said insulating sheet member is provided for covering the front face  
of said semiconductor chip and a side face of said semiconductor chip.
5. The semiconductor device according to claim 4 further  
comprising  
an opening formed in said insulating sheet member at a position  
corresponding to said electrode portion, wherein said conductive wire is  
5 connected to said electrode portion through said opening.
6. The semiconductor device according to claim 5 comprising  
a plurality of said semiconductor chips covered by said insulating  
sheet member, wherein said plurality of semiconductor chips are layered.

7. The semiconductor device according to claim 4 comprising  
a plurality of said semiconductor chips covered by said insulating  
sheet member, wherein said plurality of semiconductor chips are layered.

8. The semiconductor device according to claim 1 comprising  
a plurality of said semiconductor chips covered by said insulating  
sheet member, wherein said plurality of semiconductor chips are layered.